EVG®

Product News

Wafer Bonding System

EVG®501

Technical Data

- Substrate size: single chips to 200 mm
- Maximum contact force: up to 20 kN
- Maximum temperature: up to 450°C
- Vacuum: $1x10^{-1}$ mbar (standard), $1x10^{-5}$ mbar (optional)
- Power supply for anodic bonding: 0-2000 V, 0-50 mA

The EVG501 is a highly flexible wafer bonding system that can handle substrate sizes from pieces to 200 mm. This tool supports all common wafer bonding processes such as anodic, glass frit, solder, eutectic, transient liquid phase, and direct. The easy access bond chamber and tooling design allows for quick and easy retooling for different wafer sizes and processes with a conversion time of less than 5 minutes.

This versatility is ideal for Universities, R&D facilities, or low volume production. The basic design of the bond chambers is the same on the EVG HVM tools, such as the GEMINI, and the bonding recipes are easily transferable; this allows for easy scale up of production volumes.

Features

- Optimum total cost of ownership (TCO) for R&D and pilot line production
- Unmatched pressure and temperature uniformity
- High yield through automatic wedge compensation
- Open chamber design for fast conversion and maintenance
- High throughput with fast heating and pumping specifications
- Smallest footprint for a 200 mm bonding system: 0.8 m^2
- Standard bond chamber design from R&D - HVM allows fully recipe-compatible to EVG HVM bonding systems

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Contact

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